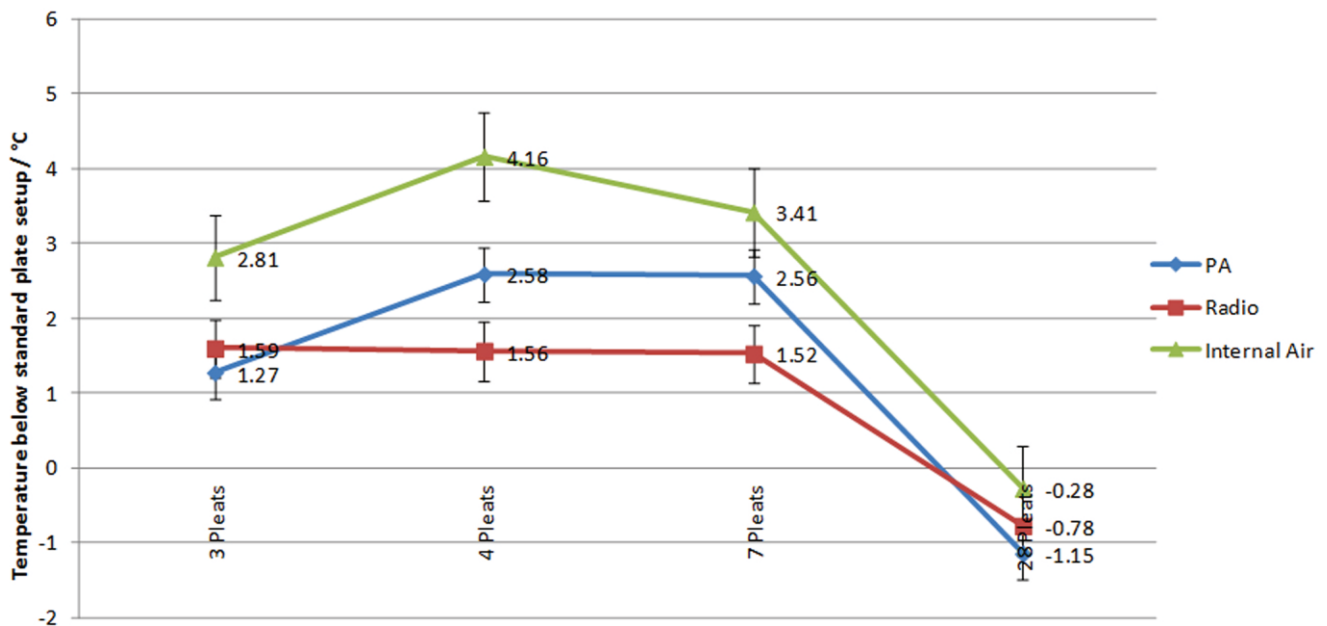


Journal of Electronics Cooling and Thermal Control

Normalised Temperature Reduction from the Standard Plate Setup for Different Outdoor Filter Pleat Densities



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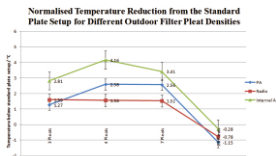
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- Radiation
- Spray cooling
- Temperature stability
- Thermal modeling of electronics systems and components

Technologies based on these transport processes such as

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